TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK3309

Switching Regulator Applications

- Low drain-source ON resistance: RDS (ON) = 0.48Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 4.3 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 450 \text{ V)}$
- Enhancement-mode: $V_{th} = 3.0 \sim 5.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	450	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$)	V _{DGR}	450	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	10	Α	
	Pulse (Note 1)	I _{DP}	40	A	
Drain power dissipat	ion (Tc = 25°C)	PD	65	W	
Single pulse avalance	the energy (Note 2)	E _{AS}	222	mJ	
Avalanche current		I _{AR}	10	Α	
Repetitive avalanche	e energy (Note 3)	E _{AR}	6.5	mJ	
Channel temperature	е	T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

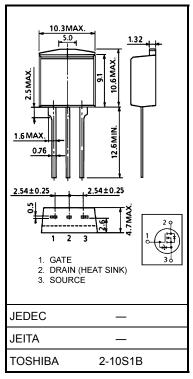
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.92	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

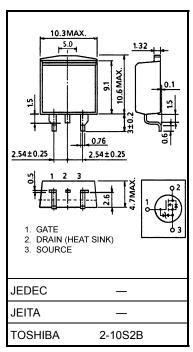
- Note 1: Please use devise on condition that the channel temperature is below 150°C.
- Note 2: $V_{DD}=90$ V, $T_{ch}=25^{\circ}C$ (initial), L = 3.7 mH, $R_{G}=25$ Ω , $I_{AR}=10$ A
- Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.





Weight: 1.5 g (typ.)



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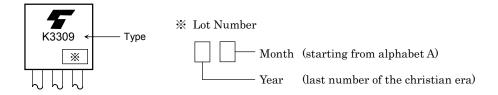
Electrical Characteristics (Ta = 25°C)

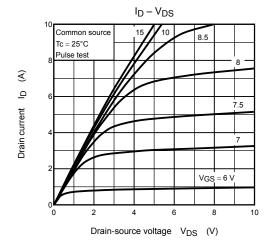
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Gate -source brea	akdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 450 V, V _{GS} = 0 V	_	_	100	μА
Drain-source brea	akdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	450 550	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	3.0		5.0	V
Drain-source ON	resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 5 A	_	0.48	0.65	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 5 A	1.5	4.3	_	S
Input capacitance	;	C _{iss}			920	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	12		pF
Output capacitance		C _{oss}		_	140		
Switching time	Rise time	t _r	$V_{GS} = 0 \text{ V}$ 0 V 0 V 0 V 0 Eq. (10) $0 \text{ RL} = 40 \Omega$ $0 \text{ Duty} \le 1\%, t_W = 10 \mu \text{s}$ 0 V	_	25	_	ns
	Turn-on time	t _{on}			35	_	
	Fall time	t _f		_	10	_	
	Turn-off time	t _{off}		_	60	_	
Total gate charge		Qg		_	23	_	nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 360 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	_	9	_	
Gate-drain charge		Q _{gd}			14	_	

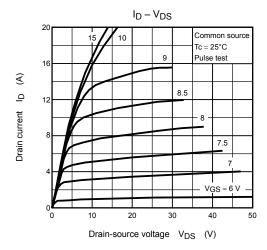
Source-Drain Ratings and Characteristics (Ta = 25°C)

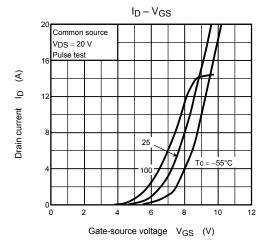
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	10	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	40	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V},$	_	280	_	ns
Reverse recovery charge	Qrr	$dI_{DR}/dt = 100 \text{ A}/\mu\text{s}$	_	2.7	_	μС

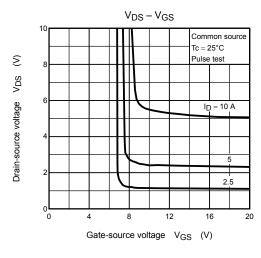
Marking

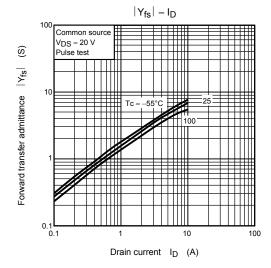


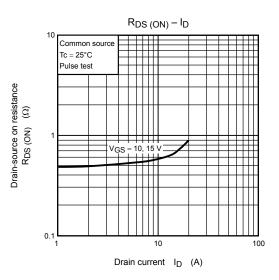


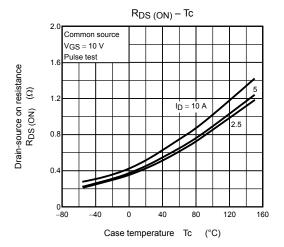


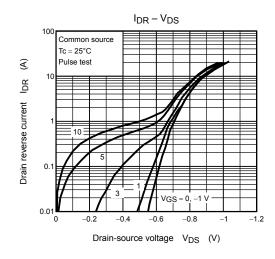


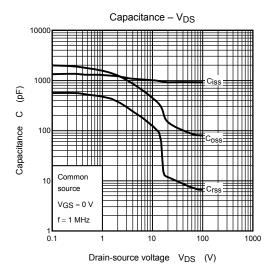


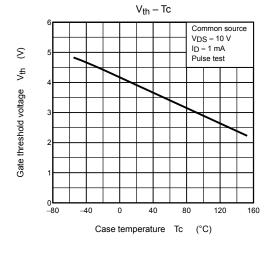


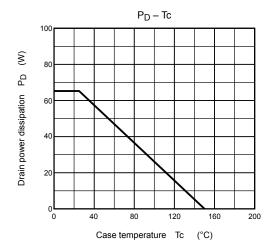


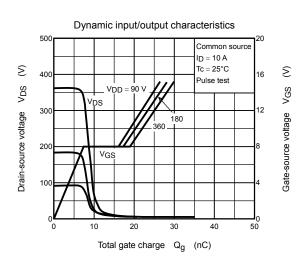


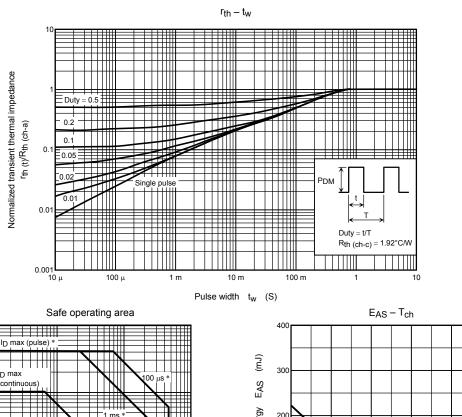


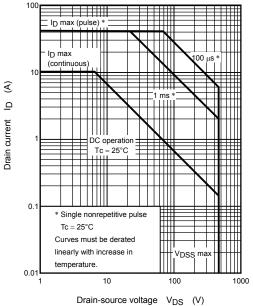


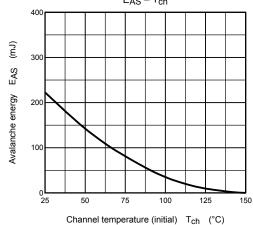


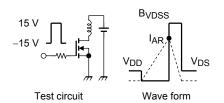












$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 3.7~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot l^2 \cdot \left(\frac{BVDSS}{BVDSS - V_{DD}} \right)$$

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